

AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

LISTING OF CLAIMS:

1-7. (cancelled)

8. (currently amended) A mold for making a composite material part, comprising:

a liquid coating of a stripping composition on the mold, wherein,

the stripping composition is a solvent-free and

the stripping composition comprises:

- 100 parts by weight of a base ingredient constituted by an epoxy polydimethylsiloxane;

- 0.5 to 10 parts by weight of a polymerization agent for polymerizing the base ingredient and constituted by a diaryliodonium salt;

- 5 to 10 parts by weight of an anti-adhesion modulator constituted by a silicone polymer, ~~present at a concentration of 5 to 10 parts by weight;~~ and

- an anti-stick agent making the composition less tacky prior to polymerization, ~~constituted~~ which comprises at least ~~by~~ one vinyl ether compound, which and said at least one vinyl ether compound is present at a concentration of 8 to 12 parts by weight in the stripping composition.

9. (previously presented) The mold according to claim 8, wherein said anti-adhesion modulator is also constituted by an epoxy polydimethylsiloxane.

10-12. (cancelled)

13. (currently amended) The mold according to claim 8, wherein

~~said stripping composition has~~ the polymerization agent
is 5 to 7 parts by weight of the polymerization agent;

said anti-adhesion modulator is an epoxy polydimethylsiloxane; and

[[.]] the anti-stick agent comprises two vinyl ether compounds, which are each present at a concentration in the range 8 to 12 parts by weight [[of]] in said stripping composition, and

said two vinyl ether compounds are a dodecyl monovinyl ether and 8 to 12 parts by weight of a cyclohexane dimethanol divinyl ether.

14. (currently amended) The mold according to claim 13, wherein ~~the stripping composition has:~~

• the polymerization agent is 6 parts by weight of the
~~polymerization agent;~~

• the anti-adhesion modulate is 8 parts by weight of
~~the anti-adhesion modulator;~~ and

• ~~the anti-stick agent comprises~~ dodecyl monovinyl ether is present at a concentration of 11.4 parts by weight of a
~~dodecyl monovinyl ether,~~ and

• the cyclohexane dimethanol divinyl ether is present
at a concentration of 11.4 parts by weight of a cyclohexane
~~dimethanol divinyl ether.~~

15. (previously presented) A wipe or cloth impregnated in a stripping composition presenting the characteristics of claim 8.

16. (currently amended) A method of molding a composite material part, comprising:

forming a composite material in a mold coated by a liquid stripping composition, wherein,

the stripping composition is a solvent-free, and

the stripping composition comprises:

• 100 parts by weight of a base ingredient constituted by an epoxy polydimethylsiloxane;

• 0.5 to 10 parts by weight of a polymerization agent for polymerizing the base ingredient and constituted by a diaryliodonium salt;

• 5 to 10 parts by weight of an anti-adhesion modulator
constituted by a silicone polymer, ~~present at a concentration of~~
~~5 to 10 parts by weight;~~ and

• an anti-stick agent making the composition less tacky prior to polymerization, ~~constituted~~ which comprises at least ~~by~~ a one vinyl ether compound, which and said one vinyl ether compound is present at a concentration of 8 to 12 parts by weight in said stripping composition.

17. (previously presented) The method according to claim 16, wherein said anti-adhesion modulator is also constituted by an epoxy polydimethylsiloxane.

18-20. (cancelled)

21. (currently amended) The method according to claim 16, wherein

~~said stripping composition has~~ the polymerization agent is 5 to 7 parts by weight ~~of the polymerization agent;~~

said anti-adhesion modulator is an epoxy polydimethylsiloxane; and

the anti-stick agent comprises two vinyl ether compounds, which are each present at a concentration in the range 8 to 12 parts by weight ~~[[of]]~~ in said stripping composition, and

said two vinyl ether compounds are a dodecyl monovinyl ether and ~~8 to 12 parts by weight of~~ a cyclohexane dimethanol divinyl ether.

22. (currently amended) The method according to claim 21, wherein ~~said stripping composition has:~~

- the polymerization agent is 6 parts by weight of the
~~polymerization agent in said stripping composition;~~

- the anti-adhesion modulator is 8 parts by weight of
~~the anti adhesion modulator in said stripping composition;~~ and

- the anti-stick agent being dodecyl monovinyl ether is
present at a concentration of 11.4 parts by weight ~~of a dodecyl~~
~~monovinyl ether,~~ and

- the cyclohexane dimethanol divinyl ether is present
at a concentration of 11.4 parts by weight of a cyclohexane
~~dimethanol divinyl ether.~~

23. (previously presented) The method according to claim 16, wherein the surface of the mold is coated with the stripping composition to a thickness of micrometer order.

24. (previously presented) The method according to claim 16, wherein the surface of the mold is coated with a wipe or a cloth impregnated in the stripping composition.

25. (previously presented) The method according to claim 16, wherein the stripping composition is polymerized under the action of ultraviolet radiation.

26. (currently amended) The method according to claim_16, wherein the stripping composition is polymerized by applying heat.

27. (previously presented) The method according to claim 26, wherein the polymerization cycle is 1 hour at 150°C ± 5°C.

28. (previously presented) The method according to claim 26, wherein the polymerization cycle is 30 minutes at 100°C.

29. (previously presented) The method according to claim 21, wherein the surface of the mold is coated with a wipe or a cloth impregnated in the stripping composition.

30. (previously presented) The method according to claim 29, wherein the stripping composition is polymerized by applying heat.

31. (previously presented) The method according to claim 16, wherein the composite material part formed in the mold is a helicopter blade or an element of such a blade.

32. (new) A mold for making a composite material part, comprising:

a molding surface comprising walls;

a liquid coating of solvent-free stripping composition on said molding surface, wherein said stripping composition comprises:

100 parts by weight of a base ingredient constituted by an epoxy polydimethylsiloxane;

0.5 to 10 parts by weight of a polymerization agent for polymerizing said base ingredient constituted by diaryliodonium salt;

5 to 10 parts by weight of an antiadhesion modulator constituted by a silicon polymer; and

an anti-stick agent constituted by a mixture of two vinyl ether compounds, and each of said two vinyl ether compounds is present at a concentration of 8 to 12 parts by weight in said stripping composition.

33. (new) The mold according to claim 32, wherein said polymerization agent is present at a concentration 6 parts by weight in said stripping composition;

said anti-adhesion modulator is present at a concentration of 8 parts by weight in said stripping composition; and

said two vinyl ether compounds are dodecyl monovinyl

ether and cyclohexane dimethanol divinyl, each are present at a concentration of 11.4 parts by weight in said stripping composition.